

10/022605

Abstract of the Disclosure:

A multichip module for leads-on-chip mounting is described.

The multichip module has a lead-frame, a common, contiguous part of a wafer slice disposed in the lead-frame, and a number  
5 of semiconductor chips disposed next to one another in the lead-frame. At least some of the semiconductor chips disposed in the lead-frame are disposed on the common, contiguous part of the wafer slice.

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